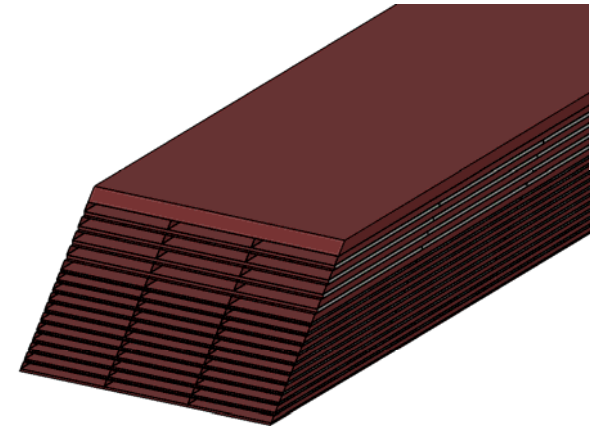


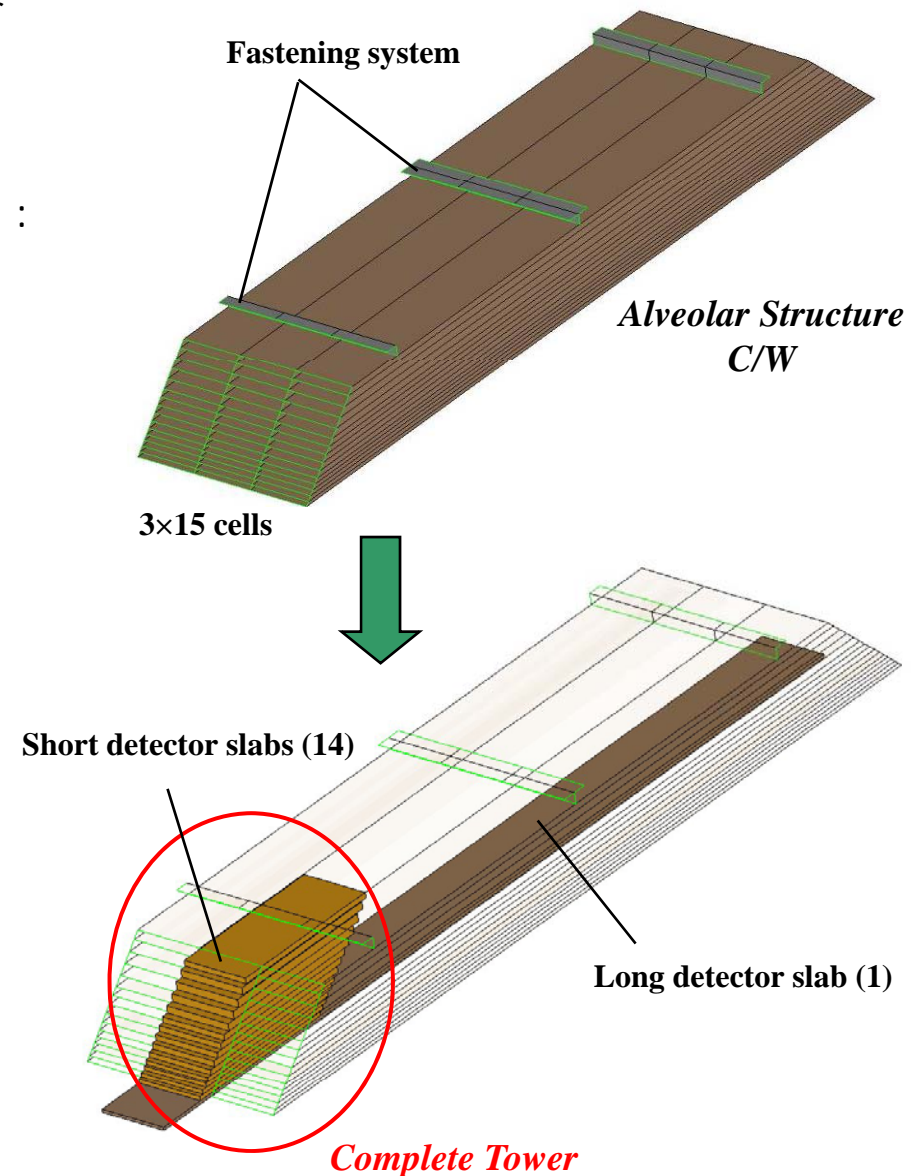
# *Mechanical Status of EUDET Module*



# Presentation of EUDET Module

Concept : to be the most representative of the final detector module :

- A alveolar composite/tungsten structure with :
  - same **W sampling**
  - 3 columns of cells to have **representative cells** in the middle of the structure (with thin composite sheets )
    - width : 124 mm ➔ **180 mm**
  - Identical global dimensions (**1.5m long**) and **shape** (trapezoidal)
  - **fastening system** ECAL/HCAL (include in the design of composite structure)
- 15 Detector slabs with **FE chips integrated**
  - **1 long** and **complete** slab ? (**L=1.3m**)
  - **14 short** slabs to obtain a complete **tower** of detection (typ. **L=40 cm**)
  - design of **compact outlet** (support system)

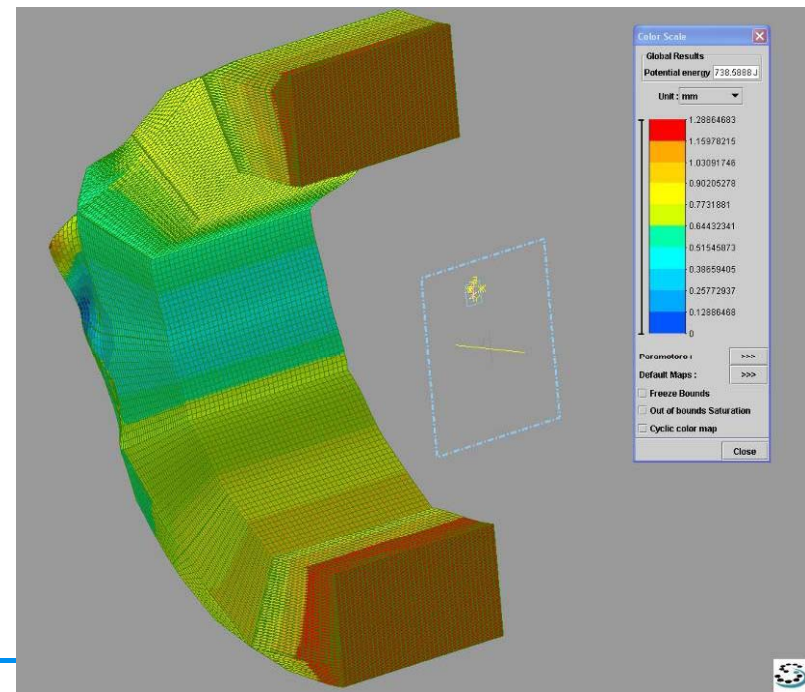
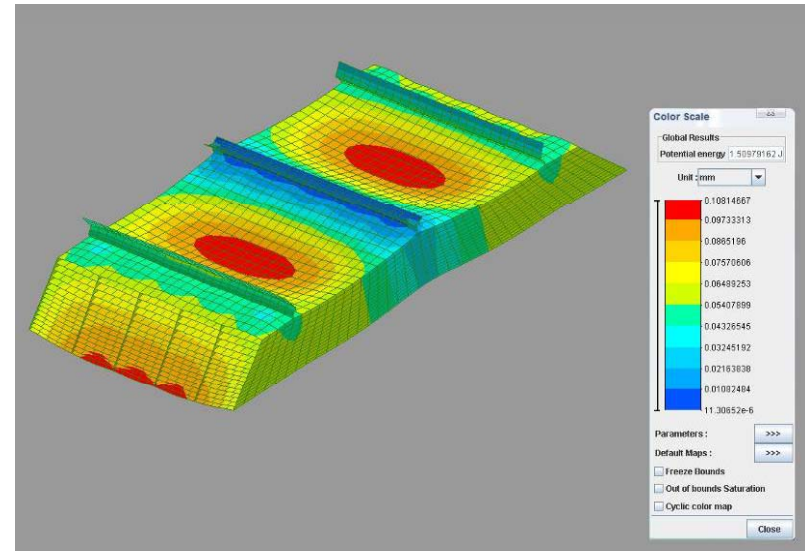


# Design of the module...

... based on mechanical simulations :

## Linear Analysis of "full scale" ECAL and HCAL modules

- **Global simulations** : global displacements and localization of high stress zone for different solutions (dimensions)
- **Local simulations** : more precise simulations and study of different local parameters to design correctly each part of this structure (**thickness** of main composite sheets, choice of **fasteners** : metal inserts, rails...)
- Check and validate simulation results by **destructive tests** for each issues



# Design of the module ...

... while taking into account **Slab Thermal analysis**

Thermal sources:

Pad size	Chan/ wafers	Ch/chip	Chip/wafer	Chip size mm <sup>2</sup>	Chan/barrel	Chan/ End-cap
5*5 mm <sup>2</sup>	144	72	2	15x15	60.4 M	21.8 M

→ CALICE ECAL: ~ **82.2 M** of channels

Assuming that the chip power is 25  $\mu$ W/channel

total power to dissipate will be : **2055 W**

⇒ external cooling OK for the "full scale ECAL"

inside each slab :

necessity of cooling system but **active** or **passive** ?

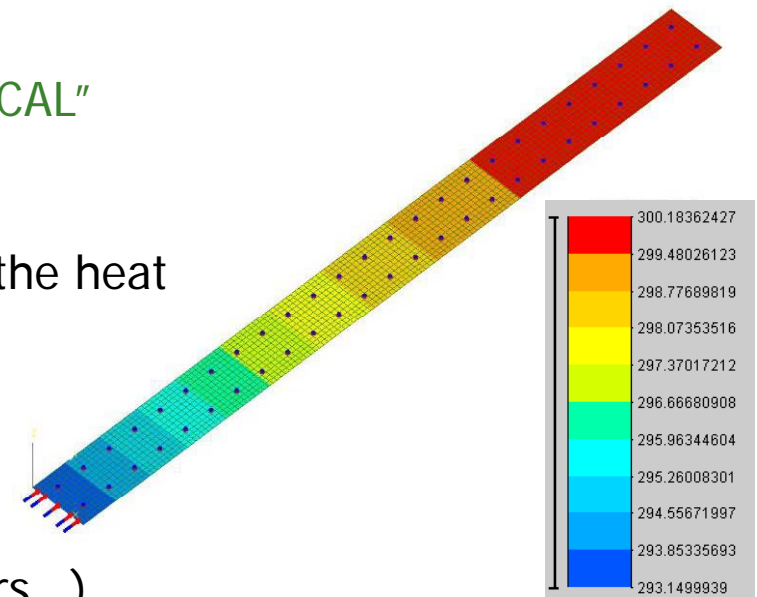
Ex: **Pessimist simulation** of heat conduction just by the heat

shield :  $\lambda = 400 \text{ W/m/K}$  (copper) ;  $S = 124 \cdot 0,4 \text{ mm}^2$   
 $L = 1,55 \text{ m}$  ;  $\Phi = 50 \cdot \Phi_{\text{chip}} = 0,18 \text{ W}$

We can estimate the temperature difference along the slab layer around **7°C** and **without contribution** of all material from slab (PCB, tungsten, carbon fibers...)

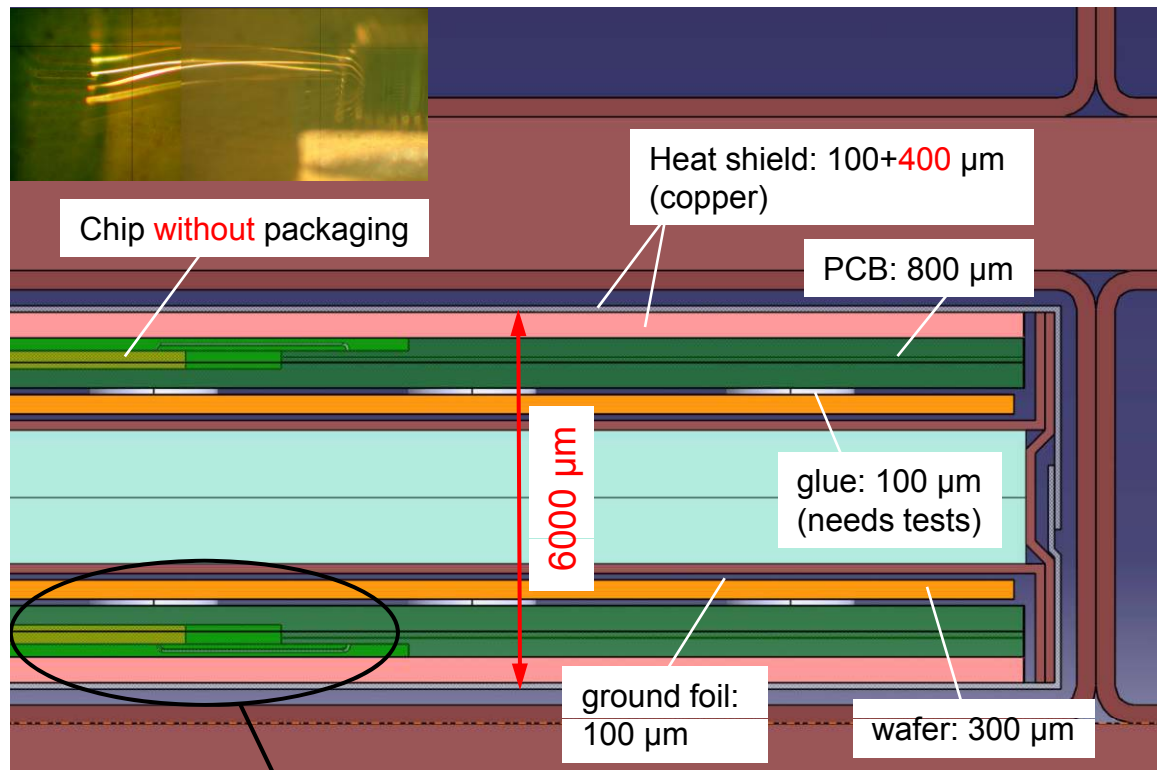
⇒ **passive cooling OK** :

**Thermal conductors** (heat shield) can be added in the slab to carry heat more efficiently along the slab direction.



# Design of the module...

... based on the definition of the detector slab :



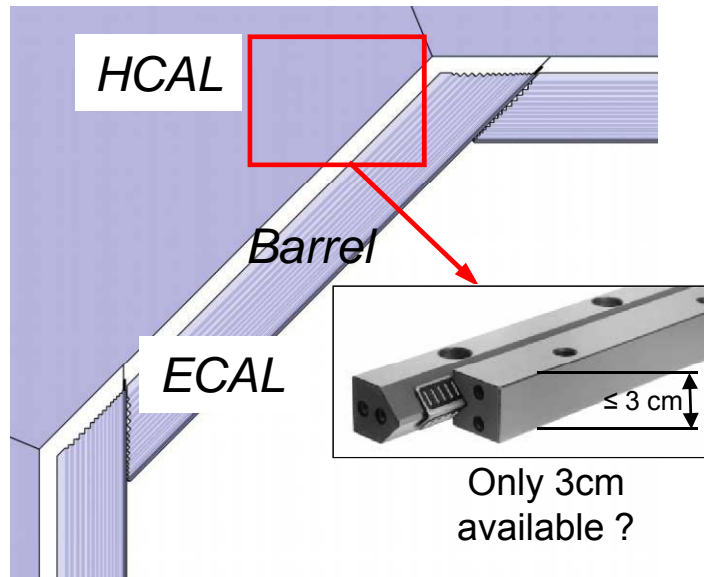
Design EUDET Slab

Chips and bonded wires  
inside the PCB

The alveolar thickness is defined by :

- ⇒ Gaps (slab integration) : 500 μm - OK
- ⇒ Heat shield : 400 μm ?  
*but real thermal dissipation (active cooling ?)*
- ⇒ PCB : 800 μm with interconnection ?
- ⇒ Thickness of glue : 100 μm ?  
*size of dots ?*
- ⇒ Thickness of wafer : 300 μm ?
- ⇒ Ground or isolate foil : 100 μm ?  
*AC vs DC ?*
- ⇒ Thickness of W : 2100 μm - OK  
and 4200 μm - OK

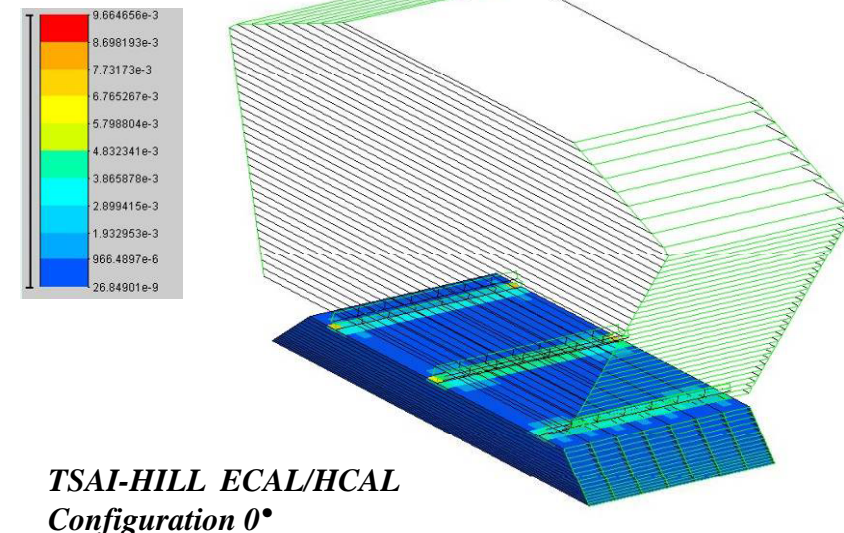
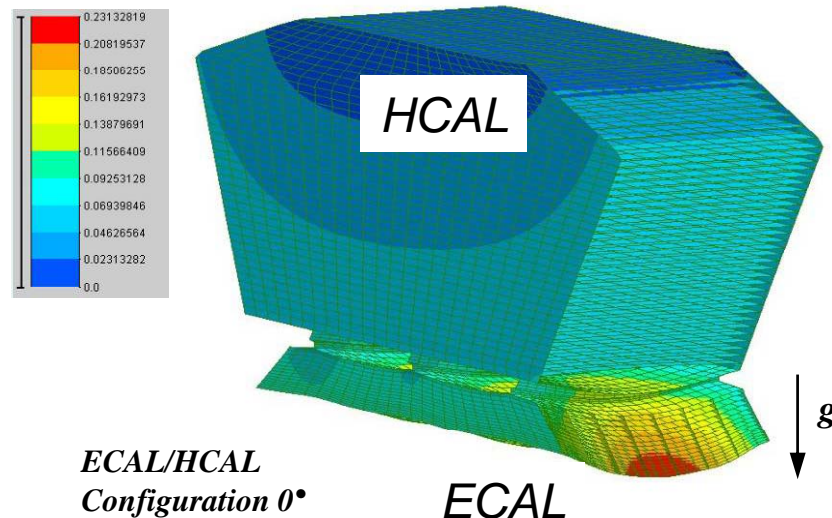
# Design of the module ...



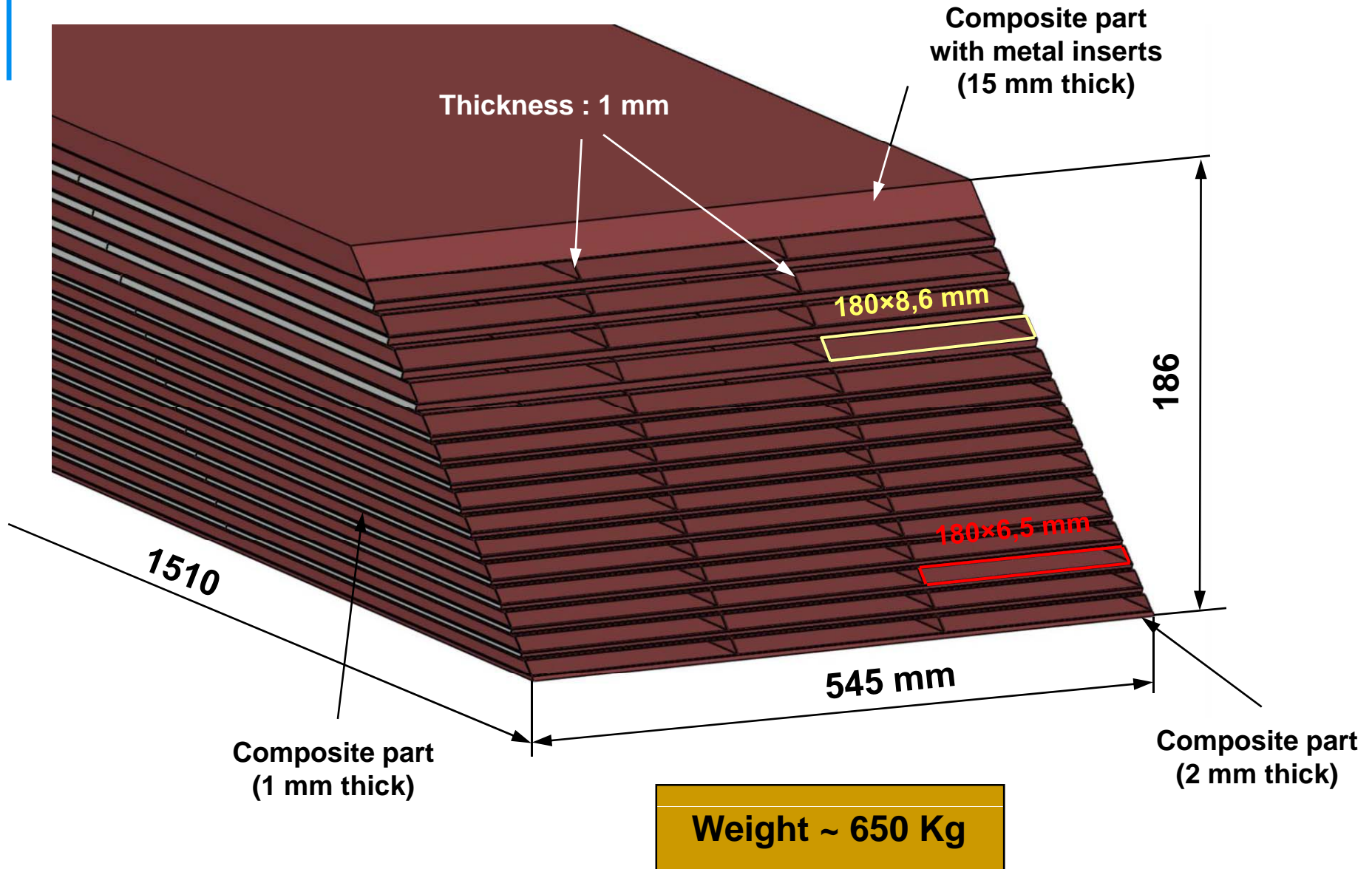
... including the ECAL/HCAL interfaces :

The fastening and connection system for the EUDET module has to be representative of the ECAL/HCAL interfaces.

- Choice of fasteners : rails directly glued on composite or metal inserts inside the structure ?
- Mechanical simulations of the ECAL/HCAL interface to take into account its influence
- Design of connection system (power supply + cooling + outlets) : backend system ?



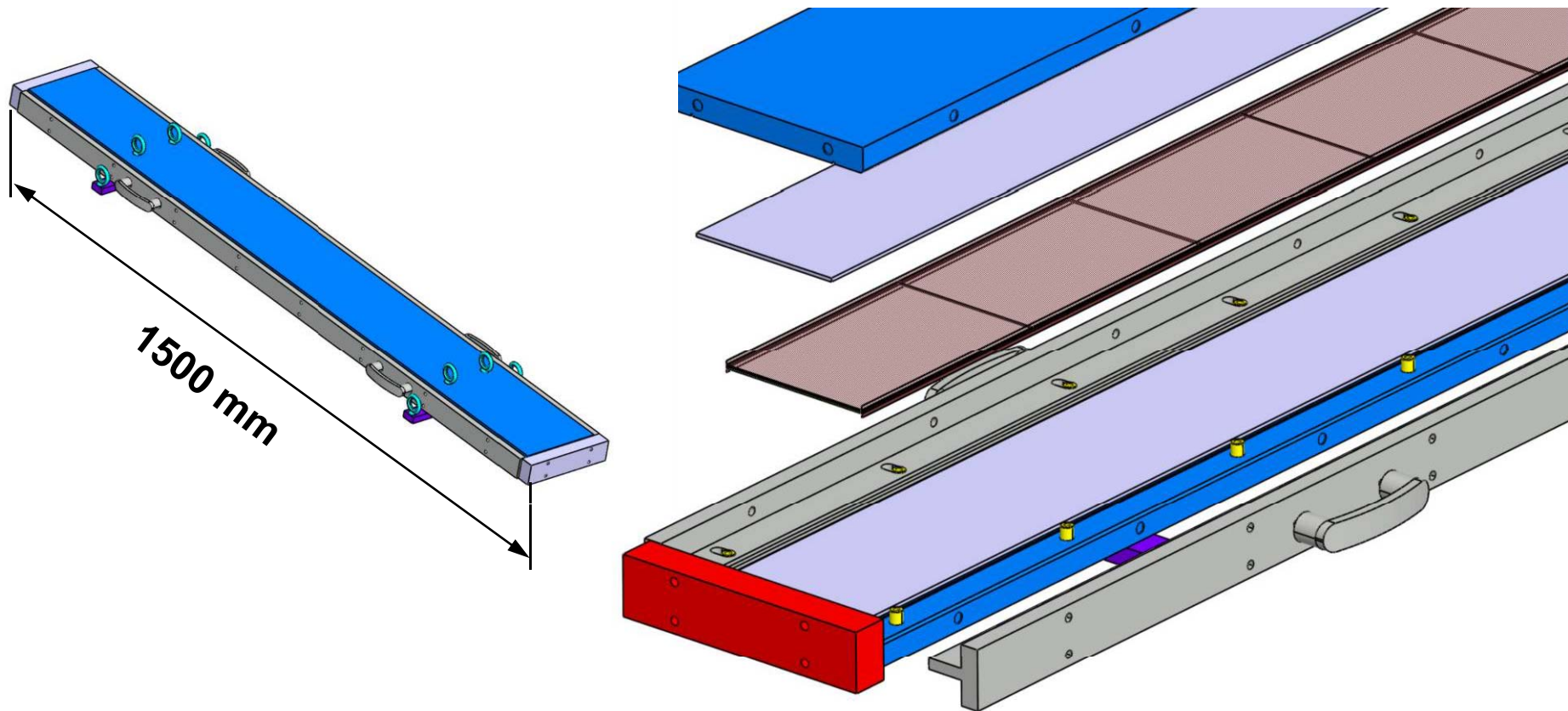
# The Design of Eudet structure



# Composite H structure

Study and definition of the long mould :

- Same principle than the mould used to do H prototype structures
- One mould for long and short structures

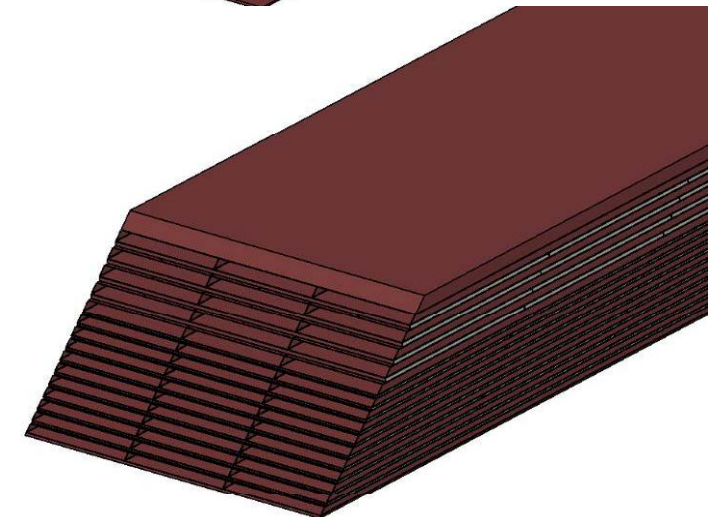
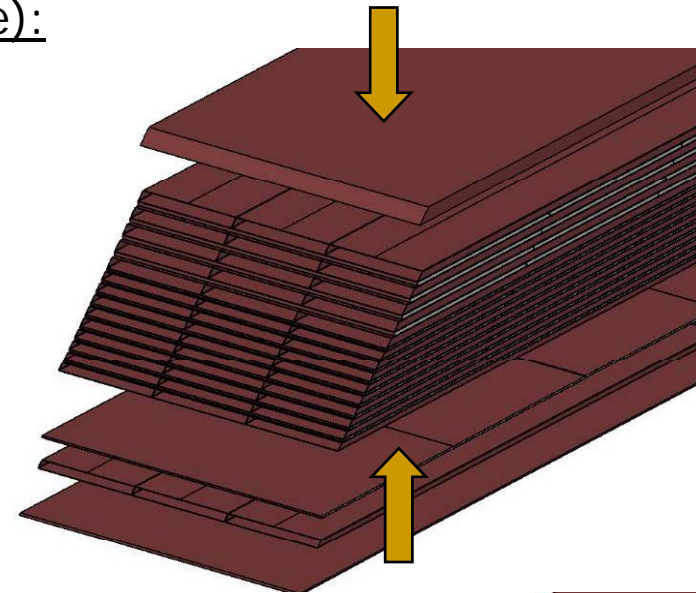




# Composite Alveolar structure

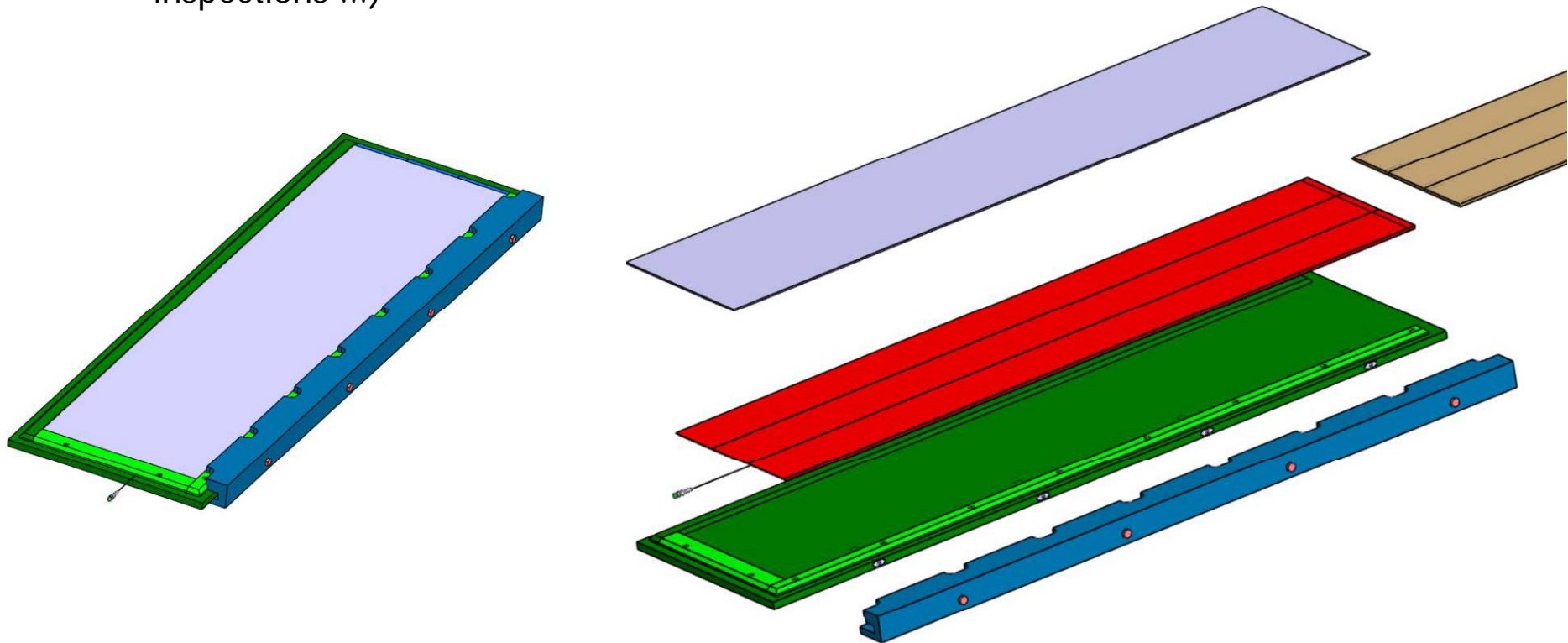
Study of different principle (with industrial expertise):

- Principle #1 : Assembled structure
  - Each alveolar layer are done **independently**, **cut** to the right length (with 45°) and **assembled** with W plates in a second curing step
    - Individual inspection and choice
    - Limit risks to lose W plates
    - Reduction of cost (simple moulds)
    - 2 polymerization process : 2 moulds
    - Mechanical ability of “gluing” structures
  
- Principle #2 : “monobloc” structure
  - **One curing step** to obtain the **final** structure
    - Final piece in one step
    - Better mechanical ability
    - Only one but more complex mould (45 cores)
    - Curing problems : thermal inertia, weigh of metal mould, control of curing parameters ...
    - Important risks to fail the structure : what about W plates ?



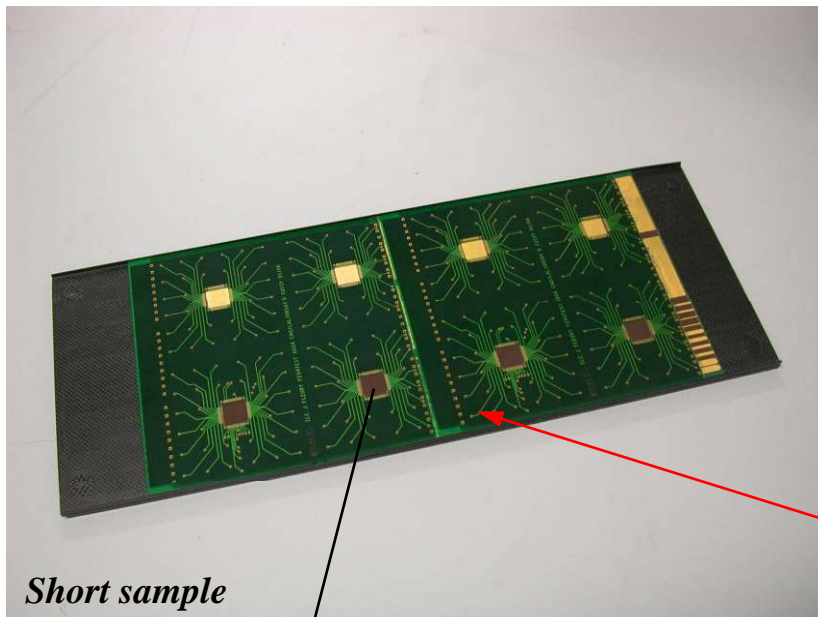
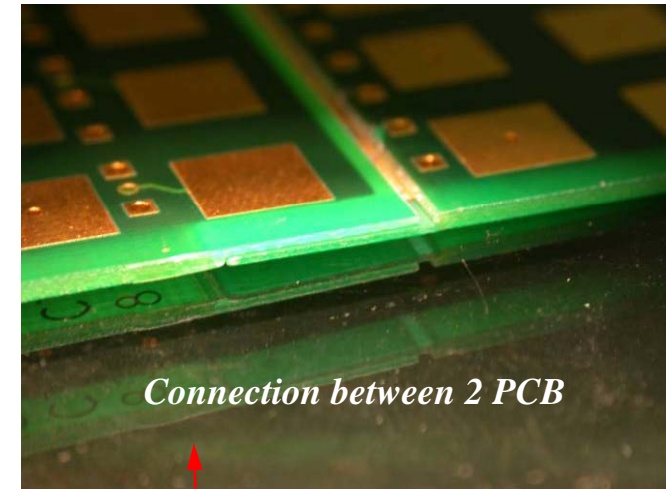
# « Alveolar layer » mould

- Study of one first concept based on principle#1 :
  - Design of one mould for **all alveolar layers**
  - Possibility to integrate **optical fiber with Bragg grating** for Tests-Simulations Dialogue
  - The **length** of each layer will be obtained by machining one side (tools)
  - First samples will use to **study mechanical behavior** (destroy tests, dimensional inspections ...)

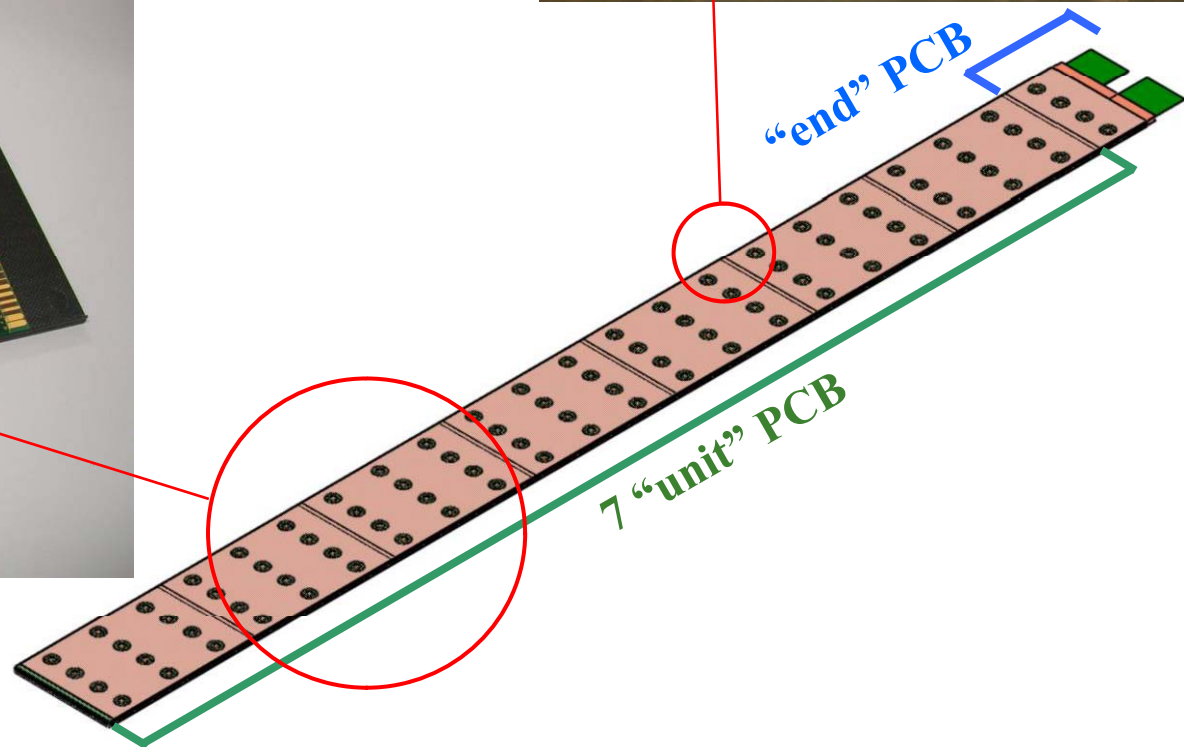


# Detector slab - principle

- Long slab is made by several short PCBs :
  - Design of one **interconnection** (glue ?)
  - Development easier : study, integration and tests of short PCB (with chips and wafers) **before assembly**
  - The **length** of each long slab will be obtained by the size of one "end PCB" (tools)



Chip « inside »



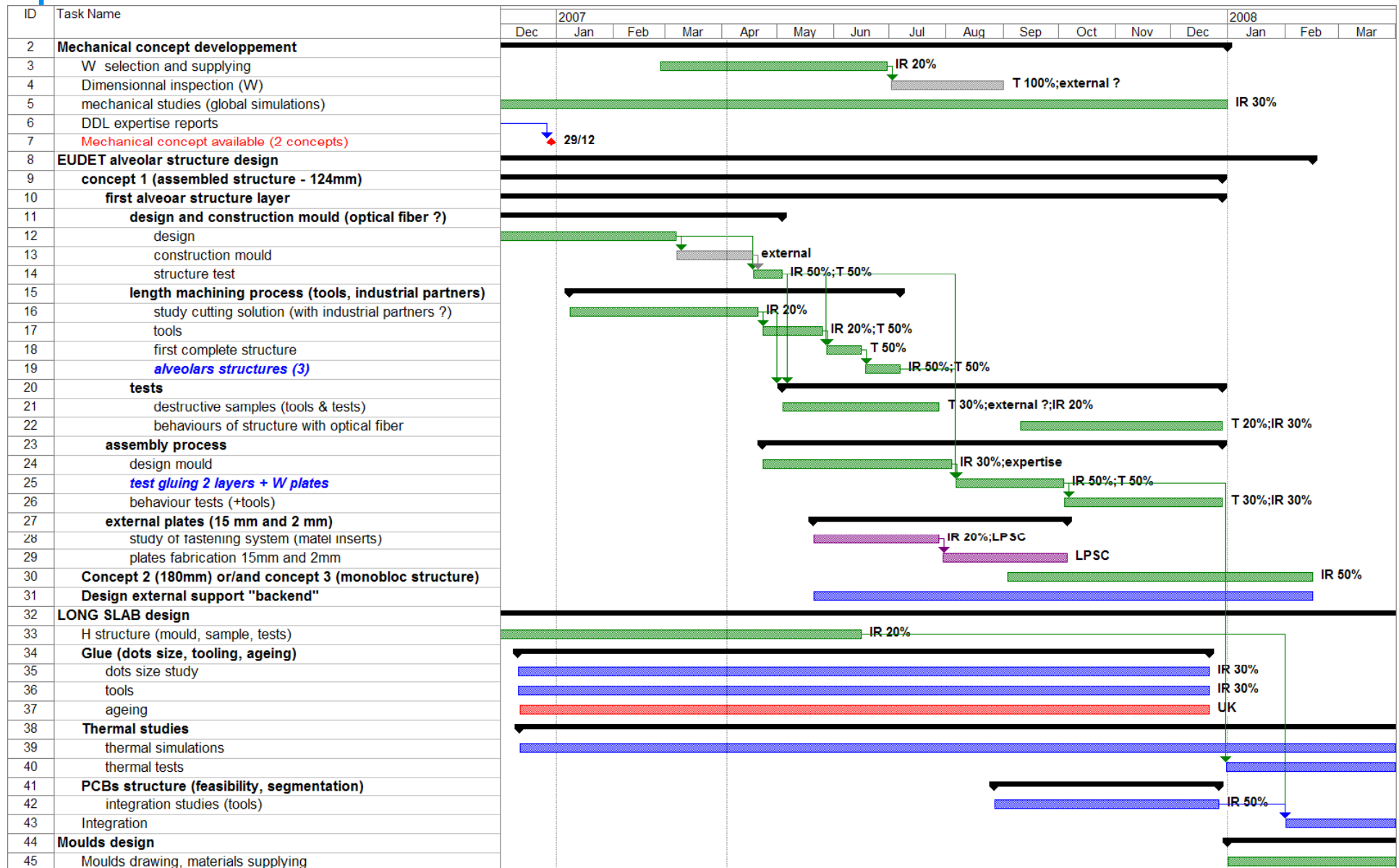
# R&D – Cost

Based on physical prototype

(EUDET part) → used

mould structure H	Internal/External	12 k€
Validation H model (20kg of W, composite)	Internal	4 k€
Design, mechanical and thermal, simulation	Internal/External	25 k€ (22 k€)
industrial partner	External	100 k€ → DDL expertise : 29 k€
Studies (fasteners, composite sheets ...)	Internal/External	20 k€
mould alveolar structure	Internal/External	120 k€ (70 k€) → 1 layer mould : 21 k€
Transport tools	Internal	8 k€
Fabrication of the structure (500 kg of W + 100 m <sup>2</sup> of composite)	Internal	75 k€ (60 k€) ; 8 k€ → 70k€ (+40 k€) ; composite : 10 k€

# Schedule 2007-2008



# *Conclusions (CdLT)*

- Nice progress recently on slab layout : choice of DC coupling and HV distribution => mechanical dimensions can be frozen
- Mechanical tooling can now proceed
- First PCB to be fabricated in fall 07
- Still in (desperate) need of EUDET Si wafers
- Manpower still critical on mechanics
- Spent : 18k€ for mould study and realization